Low Leakage Trench-based Schottky Rectifier

Features

- Fine Lithography Trench-based Schottky Technology for Very Low Forward Voltage and Low Leakage
- Fast Switching with Exceptional Temperature Stability
- Low Power Loss and Lower Operating Temperature
- Higher Efficiency for Achieving Regulatory Compliance
- High Surge Capability
- NRV Prefix for Automotive and Other Applications Requiring Unique Site and Control Change Requirements; AEC-Q101 Qualified and PPAP Capable
- These are Pb-Free and Halide-Free Devices

Typical Applications

- Switching Power Supplies including Wireless, Smartphone and Notebook Adapters
- High Frequency and DC-DC Converters
- Freewheeling and OR-ing diodes
- Reverse Battery Protection
- Instrumentation
- LED Lighting

Mechanical Characteristics:

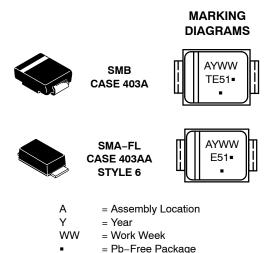
- Case: Epoxy, Molded
- Epoxy Meets Flammability Rating UL 94–0 @ 0.125 in.
- Lead Finish: 100% Matte Sn (Tin)
- Lead and Mounting Surface Temperature for Soldering Purposes: 260°C Max. for 10 Seconds
- Device Meets MSL 1 Requirements



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(Note: Microdot may be in either location)

ORDERING INFORMATION

Device	Package	Shipping†
NRVTSS5100ET3G	SMB (Pb-Free)	5000 / Tape & Reel
NRVTSAF5100ET3G	SMA-FL (Pb-Free)	5000 / Tape & Reel

+For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specification Brochure, BRD8011/D.

MAXIMUM RATINGS

Rating	Symbol	Value	Unit	
Peak Repetitive Reverse Voltage Working Peak Reverse Voltage DC Blocking Voltage	V _{RRM} V _{RWM} V _R	100	V	
Average Rectified Forward Current $(T_L = 100^{\circ}C)$	I _{F(AV)}	5.0	A	
Peak Repetitive Forward Current, (Square Wave, 20 kHz, T _L = 83°C)	I _{FRM}	10	A	
Non-Repetitive Peak Surge Current (Surge Applied at Rated Load Conditions Halfwave, Single Phase, 60 Hz)	I _{FSM}	50	A	
Storage Temperature Range	T _{stg}	-65 to +175	°C	
Operating Junction Temperature	TJ	-55 to +175	°C	
ESD Rating (Human Body Model)		1B		
ESD Rating (Machine Model)		МЗ		

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

THERMAL CHARACTERISTICS

Characteristic			Мах	Unit
Maximum Thermal Resistance, Steady State (Note 1)				°C/W
(NRVTSAF5100E) Junction-to-Lead		$R_{\theta JL}$	25	
	Junction-to-Ambient	$R_{\theta JA}$	90	
(NRVTSS5100E)	Junction-to-Lead	$R_{\theta JL}$	13.1	
	Junction-to-Ambient	R_{\thetaJA}	71.1	

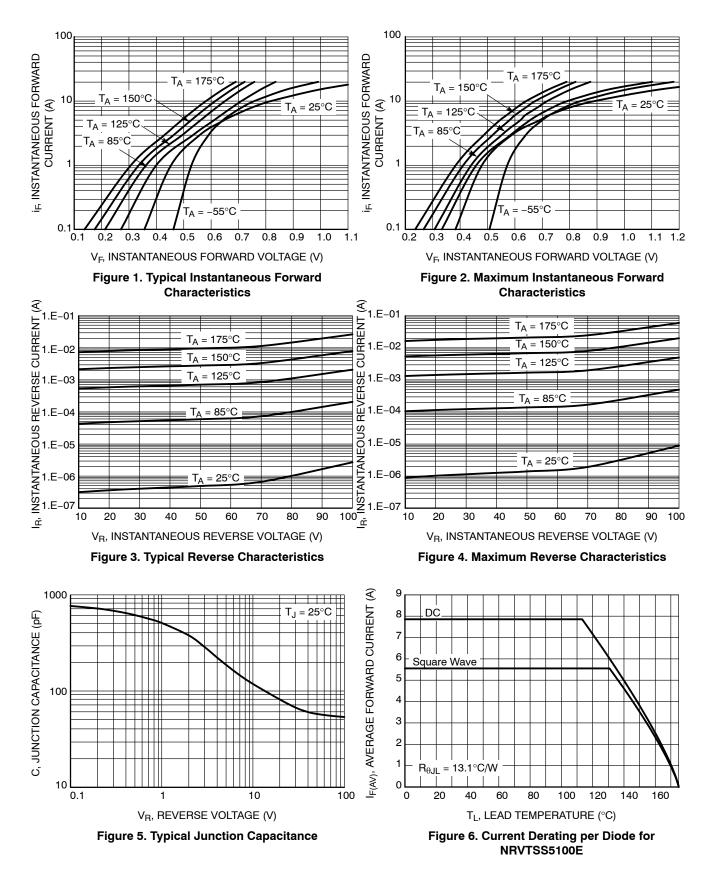
1. Assumes 600 mm² 1 oz. copper bond pad, on a FR4 board

ELECTRICAL CHARACTERISTICS

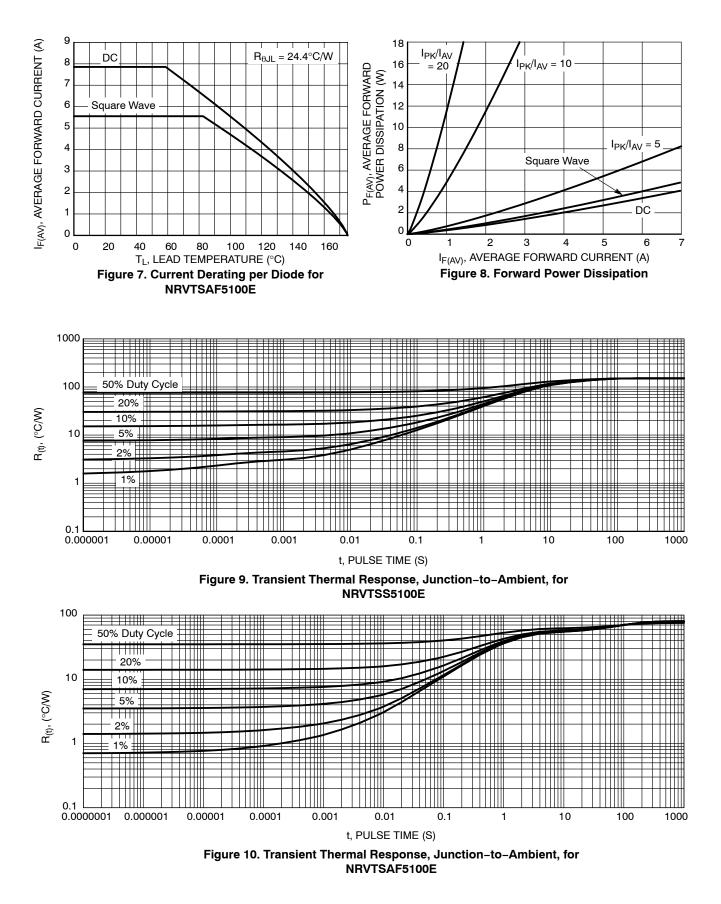
Characteristic	Symbol	Тур	Max	Unit
Instantaneous Forward Voltage (Note 2) ($i_F = 3.0 \text{ A}, T_J = 25^{\circ}\text{C}$) ($i_F = 5.0 \text{ A}, T_J = 25^{\circ}\text{C}$) ($i_F = 3.0 \text{ A}, T_J = 125^{\circ}\text{C}$) ($i_F = 5.0 \text{ A}, T_J = 125^{\circ}\text{C}$)	VF	0.56 0.65 0.50 0.56	_ 0.69 _ 0.62	V
Reverse Current (Note 2) (Rated dc Voltage, $T_J = 25^{\circ}C$) (Rated dc Voltage, $T_J = 125^{\circ}C$)	İR	2.6 2.2	9 5	μA mA
Diode Capacitance (Rated dc Voltage, T _J = 25°C, f = 1 MHz)	C _d	54.4		pF

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions. 2. Pulse Test: Pulse Width = $300 \ \mu$ s, Duty Cycle $\leq 2.0\%$.

TYPICAL CHARACTERISTICS

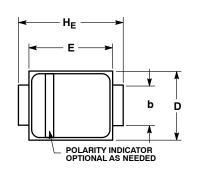


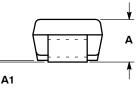
TYPICAL CHARACTERISTICS



PACKAGE DIMENSIONS

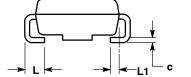
SMB CASE 403A-03 **ISSUE J**

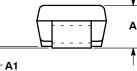




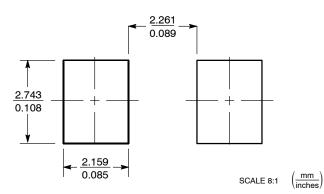
NOTES: 1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982. 2. CONTROLLING DIMENSION: INCH. 3. DIMENSION b SHALL BE MEASURED WITHIN DIMENSION L1.

	MILLIMETERS			INCHES		
DIM	MIN	NOM	MAX	MIN	NOM	MAX
Α	1.95	2.30	2.47	0.077	0.091	0.097
A1	0.05	0.10	0.20	0.002	0.004	0.008
b	1.96	2.03	2.20	0.077	0.080	0.087
С	0.15	0.23	0.31	0.006	0.009	0.012
D	3.30	3.56	3.95	0.130	0.140	0.156
E	4.06	4.32	4.60	0.160	0.170	0.181
HE	5.21	5.44	5.60	0.205	0.214	0.220
L	0.76	1.02	1.60	0.030	0.040	0.063
L1	0.51 REF			0.020 REF		





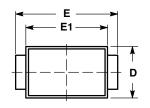
SOLDERING FOOTPRINT*



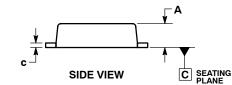
*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

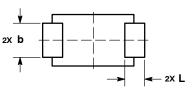
PACKAGE DIMENSIONS

SMA-FL CASE 403AA ISSUE O

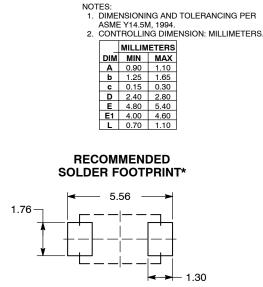












DIMENSIONS: MILLIMETERS

*For additional information on our Pb–Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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LITERATURE FULFILLMENT:

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